

Amendments to the Specification are as follows:

Please amend the paragraph on page 4, lines 6-16 as follows:

Further, as a third solving means for solving the above problems, the present invention is constructed by a surface-mounting type electronic circuit unit comprising a side electrode arranged on a side face; a circuit substrate having a wiring pattern arranged on an upper face in a state connected to this side electrode; and an electric part connected to the wiring pattern by soldering; wherein the wiring pattern has a connecting conductor electrically connecting the side electrode and the electric part, and a silk-layer fabricated by silk screen printing is formed on the connecting conductor connecting the electric part arranged in a position very near the side electrode so as to cross this connecting conductor.

Please amend the paragraph on page 8, lines 18-22 as follows:

A silk-layer fabricated by silk screen printing 7 constructed by an insulating material is formed by printing on the connecting conductor 2a having a straight line shape and connecting the electric part 4 located in the position near the side electrode 3 such that the silk-layer fabricated by silk screen printing 7 crosses this connecting conductor 2a.

Please amend the paragraph on page 9, lines 3-10 as follows:

When the electrically conductive pattern 6 and the side electrode 3 are soldered, the silk-layer fabricated by silk screen printing 7 particularly exists on the connecting conductor 2a connecting the electric part 4 arranged in the position very near the side electrode 3. Therefore, solder heat due to the soldering of the electrically conductive pattern 6 and the side electrode 3 is slightly absorbed by the silk-layer fabricated by silk screen printing 7 so that no solder heat melts the solder attaching the electric part 4 thereto.

Please amend the paragraph on page 9, lines 11-14 as follows:

Further, the flux moved on the surface of the connecting conductor 2a is prevented by the silk-layer fabricated by silk screen printing 7. Accordingly,

it is possible to remove the case that the solder attaching the electric part 4 thereto is melted by the flux.

Please amend the paragraph on page 9, lines 15-22 as follows:

Fig. 3 shows a third embodiment of the surface-mounting type electronic circuit unit of the present invention. In this third embodiment, the connecting conductor 2a connecting the electric part 4 located in the position near the side electrode 3 is formed in a bent state. Further, a silk-layer fabricated by silk screen printing 7 constructed by an insulating material is formed on this bent connecting conductor 2a by printing such that the silk layer fabricated by silk screen printing 7 crosses this connecting conductor 2a.

Please amend the paragraph on page 11, lines 15-24 as follows:

Further, the surface-mounting type electronic circuit unit of the present invention comprises a side electrode arranged on a side face; a circuit substrate having a wiring pattern arranged on an upper face in a state connected to this side electrode; and an electric part connected to the wiring pattern by soldering; wherein the wiring pattern has a connecting conductor electrically connecting the side electrode and the electric part, and a silk-layer fabricated by silk screen printing is formed on the connecting conductor connecting the electric part arranged in a position very near the side electrode so as to cross this connecting conductor.

Please amend the paragraph beginning on page 11, line 25 and ending on page 12, line 8 as follows:

Since the silk-layer fabricated by silk screen printing layer thus exists on the connecting conductor connecting the electric part arranged in the position very near the side electrode, solder heat due to the soldering of the electrically conductive pattern and the side electrode is slightly absorbed by the silk-layer fabricated by silk screen printing so that no solder heat melts the solder attaching the electric part thereto. Further, the flux moved on the surface of the connecting conductor is prevented by the silk-layer fabricated by silk screen printing. Accordingly, it is possible to remove the case that the solder attaching the electric part thereto is melted by the flux. Therefore, the surface-mounting type electronic circuit unit of high reliability can be provided.

Please amend the Abstract of the Disclosure as follows:

ABSTRACT OF THE DISCLOSURE

~~The present invention provides a surface-mounting type electronic circuit unit having no melting of solder attaching an electric part thereto and having high reliability. Therefore, t~~
The surface-mounting type electronic circuit unit of the present invention has a side electrode arranged on a side face; a circuit substrate having a wiring pattern arranged on an upper face in a state connected to this side electrode; and an electric part connected to the wiring pattern by soldering. A connecting conductor of the wiring pattern connecting the electric part arranged in a position very near the side electrode is formed in a bent state. Therefore, the connecting conductor between the side electrode and the electric part can be lengthened. Accordingly, solder heat due to the soldering of an electrically conductive pattern and the side electrode and the heat of a flux fall on the electric part side, and an influence on the solder attaching the electric part thereto is small so that this solder is not melted and the surface-mounting type electronic circuit unit of high reliability is obtained.